



SOT353

plastic surface-mounted package; 5 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SOT353
Package type industry code	TSSOP5
Package style descriptive code	SOT (small outline transistor)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEITA package outline code	SC-88A
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.8	-	2	2.2	mm
E	package width	1.15	-	1.25	1.35	mm
A	seated height	0.8	-	0.95	1.1	mm
n ₂	actual quantity of termination	-	-	5	-	



2. Package outline

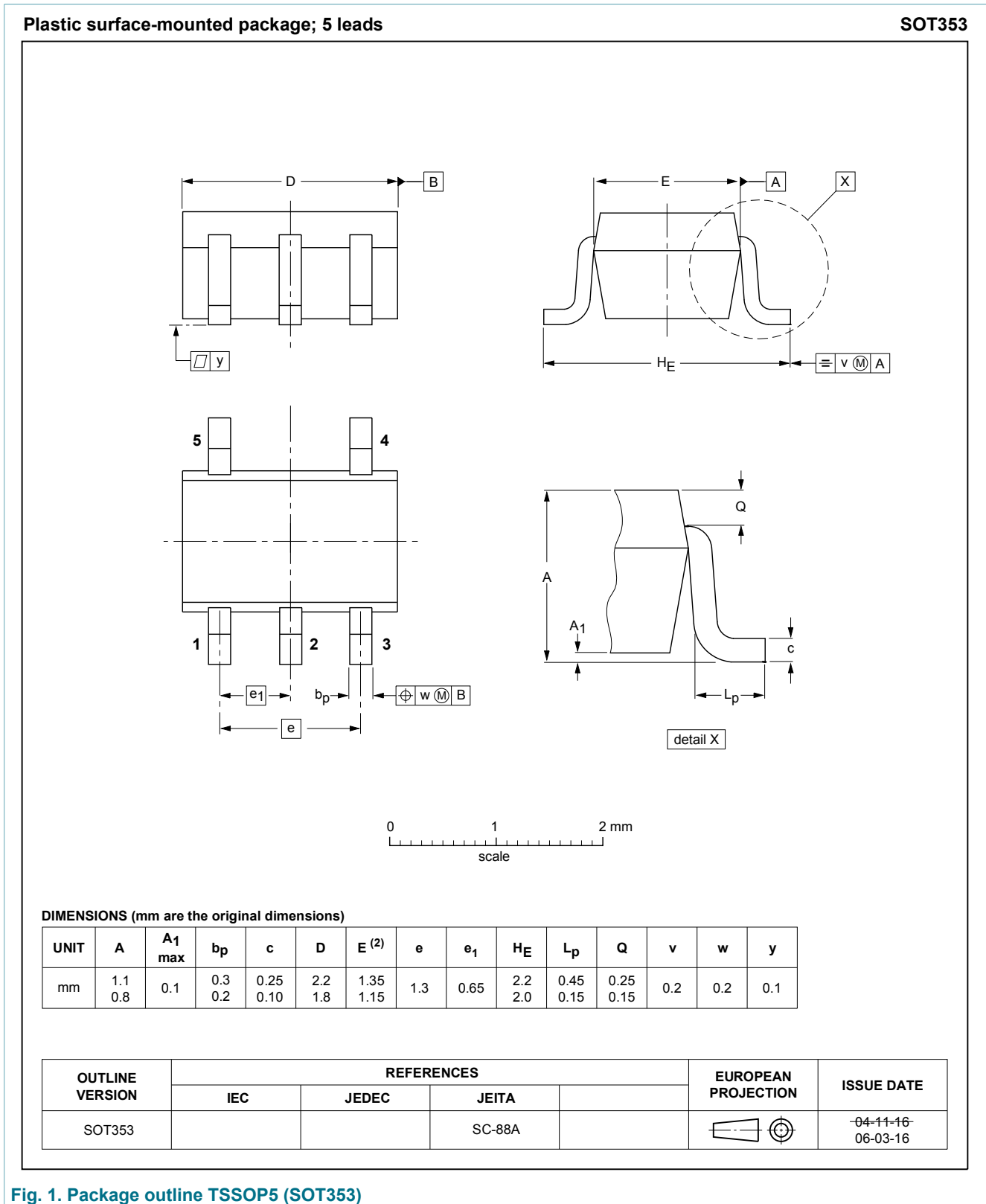


Fig. 1. Package outline TSSOP5 (SOT353)

3. Soldering

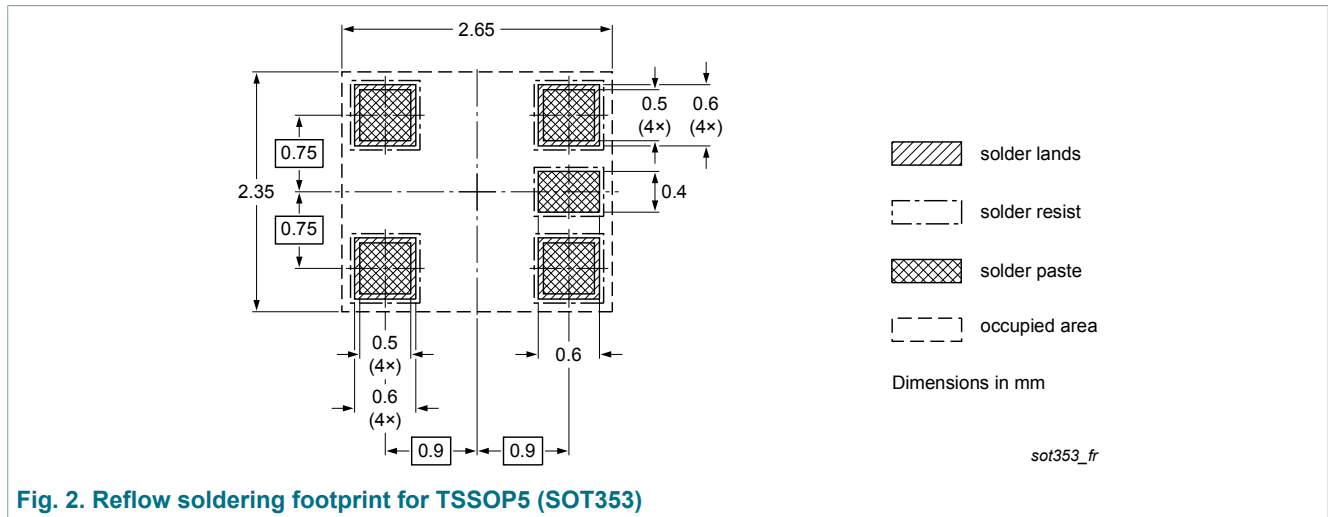


Fig. 2. Reflow soldering footprint for TSSOP5 (SOT353)

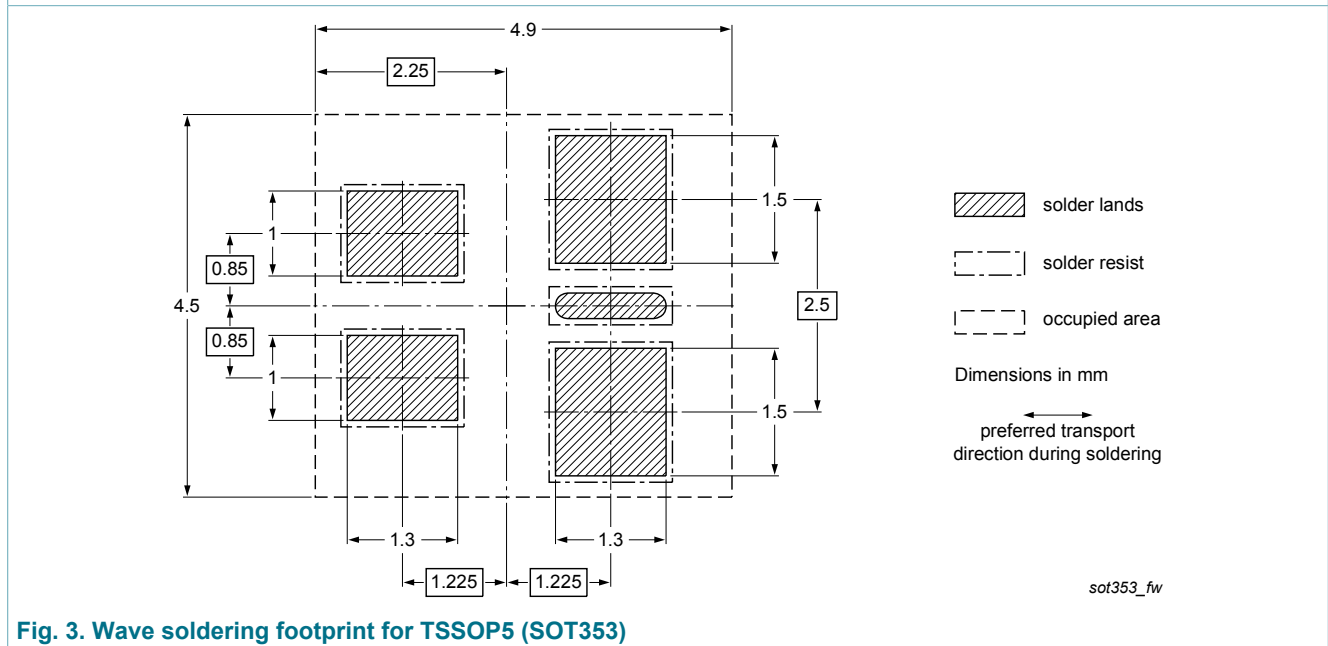


Fig. 3. Wave soldering footprint for TSSOP5 (SOT353)

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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